VOLTAGE	APPLICA	BLE STAN	DARD							
TEMPERATURE RANGE				150V AC c		CURRENT		1A		
RATING				-35°C TO + 85°C (NOTE 1	\			-10°C TO + 60°C (NOTE		3)
APPLICABLE   DF13-#S-1.25C   APPLACABLE   CRIMP CONTACT   DF13-2630SCFA (05)	RATING	OPERATING		20% TO 80%(NOTE 2)		STORAGE		·		
SPECIFICATIONS  ITEM TEST METHOD REQUIREMENTS OT  CONSTRUCTION  GENERAL EXAMINATION VISUALLY AND BY MEASURING INSTRUMENT ACCORDING TO DRAWING.  MARKING COMPETED VISUALLY SIDE OF THE STANDARD		APPLICABLE		APP		PPLAICABL	E			
SPECIFICATIONS  ITEM TEM TEST METHOD REQUIREMENTS OT  CONSTRUCTION  SENERAL EXAMINATION (INSUALLY AND BY MEASURING INSTRUMENT). ACCORDING TO DRAWING.  X  ELECTRIC CHARACTERISTICS  CONTACT RESISTANCE 100m A (DC OR 1000 Hz). 30m/2 MAX.  INSULATION RESISTANCE 100m A (DC OR 1000 Hz). 30m/2 MAX.  X  INSULATION RESISTANCE 100m A (DC OR 1000 Hz). 30m/2 MAX.  X  INSULATION RESISTANCE 100m A (DC OR 1000 Hz). 30m/2 MAX.  X  MECHANICAL CHARACTERISTICS  MECHANICAL 50TIMES INSERTIONS AND EXTRACTIONS. 0F PARTS.  O'TS mm., A1 2 h, FOR 3 DIRECTIONS. 0F PARTS.  O'TS mm., A1 2 h, FOR 3 DIRECTIONS. 30M/2 MAX.  VIBRATION FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 30 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO ELECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO ELECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  SHOCK ACCELARRATION OF 480 m/s*, 11 ms DUARATION, 10 NO BLECTRICAL DISCONTINUITY OF 1 js. 5.  ENVIRONMENTAL CHARACTERISTICS  RAPID CHANGE OF TEMPERATURE 55 -> 5 TO 35 -> 5	CONNECTOR		DI 13-+3-1. 200							
ITEM										
CONSTRUCTION  GENERAL EXAMINATION  MARKING  CONFIRMED VISUALLY.  ELECTRIC CHARACTERISTICS  CONTACT RESISTANCE  100m A (DC OR 1000 Hz).  MISULATION  RESISTANCE  VOLTAGE PROOF  MECHANICAL  OPERATION  FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE  0.75 mm. AT 2 n, FOR 3 DIRECTIONS.  SHOCK  ACCELARRATION OF 490 m/s², 11 ms DUARATION.  SO DAMAGE, CRACK OR LOOSENESS  OF PARTS.  CONTACT RESISTANCE  SOMM MAX.  X  X  CONTACT RESISTANCE  SOMM MAX.  X  CONTACT RESISTANCE  SOMM MAX.  X  CONTACT RESISTANCE  SOMM MAX.  X  X  CONTACT RESISTANCE  SOMM MAX.  X  CONTACT RESISTANCE  SOMM MAX.  X  SOMMARGE, CRACK OR LOOSENESS  OF PARTS.  CONTACT RESISTANCE  SOMM MAX.  X  CONTACT RESIST	ITEM									AT
MARKING  CONFIRMED VISUALLY.  ELECTRIC CHARACTERISTICS  CONTACT RESISTANCE  100m A (DC OR 1000 Hz).  INSULATION  RESISTANCE  VOLTAGE PROOF  SOUV AC FOR 1 min.  MO FLASHOVER OR BREAKDOWN.  X  MECHANICAL CHARACTERISTICS  MECHANICAL  OPERATION  FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE  0.75 mm, AT 2 h, FOR A DIRECTIONS.  SHOCK  ACCELARATION OF 490 m/s², 11 ms DUARATION.  SINE HALF-WAVE, 3 CYCLES IN 3 BOTH AXISES; 18 TIMES IN TOTAL.  ENVIRONMENTAL CHARACTERISTICS  MECHANICAL  SOUND AMAGE, CRACK OR LOOSENESS  OF PARTS.  SHOCK  ACCELARATION OF 490 m/s², 11 ms DUARATION.  SINE HALF-WAVE, 3 CYCLES IN 3 BOTH AXISES; 18 TIMES IN TOTAL.  ENVIRONMENTAL CHARACTERISTICS  RAPID CHANGE OF  TEMPERATURE  TIME  30 -5 TO 15 -30 -5 TO 15 min  UNDER 5 CYCLES  DAMP HEAT  (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (CONTACT RESISTANCE: 30mm; MAX.  (2) INSULATION RESISTANCE: 30mm; MAX.  (3) INSULATION RESISTANCE: 30mm; MAX.  (4) INSULATION RESISTANCE: 30mm; MAX.  (5) INSULATION RESISTANCE: 30mm; MAX.  (6) TO ADAMAGE, CRACK OR LOOSENESS  OF PARTS.  DAMP HEAT  (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (1) CONTACT RESISTANCE: 30mm; MAX.  (2) INSULATION RESISTANCE: 30mm; MAX.  (3) INSULATION RESISTANCE: 30mm; MAX.  (4) INSULATION RESISTANCE: 30mm; MAX.  (5) INSULATION RESISTANCE: 30mm; MAX.  (6) INSULATION RESISTANCE: 30mm; MAX.  (7) INSULATION RESISTANCE: 30mm; MAX.  (8) INSULATION RESISTANCE: 30mm; MAX.  (9) INSULATION RESISTANCE: 30mm; MAX.  (1) INSULATION RESISTANCE: 30mm; MAX.  (2) INSULATION RESISTANCE: 30mm; MAX.  (3) INSULATION RESISTANCE: 30mm; MAX.  (3) INSULATION RESISTANCE: 30mm; MAX.  (3) INSULATION RESISTANCE: 30mm; MAX.  (4) INSULATION RESISTANCE: 30mm; MAX.  (5) INSULATION RESISTANCE: 30mm; MAX.  (6) INSULATION RESISTANCE: 30mm; MAX.  (7) INSULATION RESISTANCE: 30mm; MAX.  (8) INSULATION RESISTANCE: 30mm; MAX.  (9) INSULATION RESISTANCE: 30mm; MAX.  (1) INSULATION RESISTANCE: 30mm; MAX.  (1) INSULATION RESISTANCE: 30mm; MAX.  (2) INSULATION RESISTANCE: 30mm; MAX.  (3) INSULATION RESISTANCE: 30mm;										7
ELECTRIC CHARACTERISTICS						ACCO	ACCORDING TO DRAWING.			Х
SOUNTACT RESISTANCE   100m A (DC OR 1000 Hz).   30mm MAX.   X										X
INSULATION   100V DC   500MΩ MIN   X   X   VOLTAGE PROOF   500V AC FOR 1 min.   NO FLASHOVER OR BREAKDOWN.   X   X   VOLTAGE PROOF   500V AC FOR 1 min.   NO FLASHOVER OR BREAKDOWN.   X   X   VOLTAGE PROOF   500V AC FOR 1 min.   NO FLASHOVER OR BREAKDOWN.   X   X   VOLTAGE PROOF   500V AC FOR 1 min.   NO FLASHOVER OR BREAKDOWN.   X   X   VOLTAGE PROOF   500V AC FOR 1 min.   X   X   X   VOLTAGE PROOF   500V AC FOR 1 min.   X   X   X   VOLTAGE PROOF   500V AC FOR 1 min.   X   X   NO DAMAGE, CRACK OR LOOSENESS OF PARTS.   2 NO DAMAGE, CRACK OR LOOSENESS OF PARTS.   2 NO DAMAGE, CRACK OR LOOSENESS OF PARTS.   3 NO ELECTRICAL DISCONTINUITY OF 1 μs.   3 NO PARTS.   3 NO DAMAGE, CRACK OR LOOSENESS OF PARTS.   3 NO DAMAGE, CRACK OR LOOSENESS OR PARTS.   3 NO DAMAGE, CRACK OR LOOSENESS OR PARTS.   3 NO DAMAGE,						30mΩ	30mO MAX			
RESISTANCE VOLTAGE PROOF  500V AC FOR 1 min.  NO FLASHOVER OR BREAKDOWN.  X  MECHANICAL OPERATION  5071MES INSERTIONS AND EXTRACTIONS.  (1) CONTACT RESISTANCE: 30mΩ MAX. (2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  VIBRATION  FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.  SHOCK  ACCELAERATION OF 490 m/s′, 11 ms DUARATION, 10 NO ELECTRICAL DISCONTINUITY OF 1µs. SINE HALF-WAVE, 3 CYCLES IN 3 BOTH AXISES; 18 TIMES IN TOTAL.  ENVIRONMENTAL CHARACTERISTICS  RAPID CHANGE OF TEMPERATURE 30→ 5 TO 15 →30→ 5 TO 15 min UNDER 5 CYCLES.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (3) CONTACT RESISTANCE: 30mΩ MAX. (2) INSULATION RESISTANCE: 30mΩ MAX. (2) INSULATION RESISTANCE: 30mΩ MAX. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (3) CONTACT RESISTANCE: 30mΩ MAX. (2) INSULATION RESISTANCE: 30mΩ MAX. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  CONTACT RESISTANCE TO 30 DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.  SOLDERING HEAT  250±5°CMAX. FOR 10 SECONDS.  SOLDERING HEAT  250±5°CM AX FOR 10 SECONDS.  SOLDERING HEAT  SOLDERED AT SOLDER TEMPERATURE, 20±15°C. FOR 3 SECONDS  SOLDER SHALL COVER A MINIMUM OF 215±5°C FOR INSERTION DURATION, 3 SECONDS.  SOLDER SHALL COVER A MINIMUM OF 05 % OF THE SURFACE BEING IMMERSED.  X  TERMINALS.  COUNT  DESCRIPTION OF REVISIONS  DESIGNED  CHECKED  M. WELLOW  THE SURFACE BEING IMMERSED.  X  PAPROVED  KI. MINIMUM 11. 03  CHECKED  M. WELLOW  THE SURFACE BEING IMMERSED.  X  CHECKED  M. WELLOW  TERMINALS.  DESIGNED  SHALL COVER A MINIMUM OF 11. 03  DESIGNED			, ,							<u> </u>
MECHANICAL CHARACTERISTICS  MECHANICAL    Sotimes insertions and extractions.   ⊕ Contact resistance: 30mΩ Max.   2 No Damage. Crack or Looseness x x of Parts.   ⊕ Contact resistance: 30mΩ Max.   2 No Damage. Crack or Looseness x x of Parts.   ⊕ Contact resistance: 30mΩ Max.   2 No Damage. Crack or Looseness x x of Parts.   ⊕ Contact resistance: 30mΩ Max.   2 No Damage. Crack or Looseness x x of Parts.   ⊕ Contact resistance: 30mΩ Max.   2 No Damage. Crack or Looseness x x of Parts.   ⊕ Contact resistance: 30mΩ Max.   2 No Damage. Crack or Looseness x x of Parts.   ⊕ Contact resistance: 30mΩ Max.   2 No Damage. Crack or Looseness x x of Parts.   ⊕ Contact resistance: 30mΩ Max.   2 No Damage. Crack or Looseness x x of Parts.   ⊕ Contact resistance: 30mΩ Max.   2 No Damage. Crack or Looseness x x   ⊕ Parts.   ⊕ Par			100V DC.			DOUNIC	SOUNIS INTIN.			-
MECHANICAL OPERATION   SoTIMES INSERTIONS AND EXTRACTIONS.   ① CONTACT RESISTANCE: 30mΩ MAX.   ② NO DAMAGE, CRACK OR LOGSENESS OP PARTS.   OF PART	VOLTAGE PROOF		500V AC FOR 1 min.			NO FL	NO FLASHOVER OR BREAKDOWN.			
OPERATION    OPERATION   OPERATS.   OPERATS.   OPERATS.										
VIBRATION  FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE  0.75 mm, AT 2 h, FOR 3 DIRECTIONS.  C) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  SHOCK  ACCELAERATION OF 490 m/s′, 11 ms DUARATION.  SINE HALF-WAVE, 3 CYCLES IN 3 BOTH AXISES; 15 TIMES IN TOTAL.  ENVIRONMENTAL CHARACTERISTICS  RAPID CHANGE OF TIME 30 → 5 TO 15 →30 → 5 TO 15 min UNDER 5 CYCLES.  DAMP HEAT UNDER 5 CYCLES.  DAMP HEAT EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  C) CONTACT RESISTANCE: 50 MMΩ MM. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  C) CONTACT RESISTANCE: 50 MMΩ MM. (2) INSULATION RESISTANCE: 50 MMΩ MM. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  C) CONTACT RESISTANCE: 30 MMΩ MM. (2) INSULATION RESISTANCE: 50 MMΩ MM. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  RESISTANCE TO 1) FLOW SOLDERING NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF PARTS.  SOLDERING HEAT 250±5°CMAX. FOR 10 SECONDS.  SOLDERABILITY SOLDER TEMPERATURE, 215±5°C FOR INSERTION DURATION, 3 SECONDS.  SOLDERABILITY SOLDERE TEMPERATURE, 215±5°C FOR INSERTION DURATION, 3 SECONDS.  REMARKS  NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT.  NOTE 2:INCLUDING THE TEMPERATURE RISE BY CURRENT.  NOTE 2:INCLUDING THE TEMPERATURE RISE BY CURRENT.  NOTE 2:INCLUDING THE TEMPERATURE RISE BY CURRENT.  NOTE 2:NO CONDENSING.  NOTES:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS  BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE FOR UNUSED PRODUCTS  BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE FOR UNUSED PRODUCTS  BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION.  COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED HK. UMEHARA 11. 03 DESIGNED TS. KUMIAZAMA 11. 03 DESIGNED TS. KUMIAZAMA 11. 03 DESIGNED TS. K			50TIMES INSERTIONS AND EXTRACTIONS.			-	_			
0.75 mm, AT 2 h, FOR 3 DIRECTIONS.   ② NO DAMAGE, CRACK OR LOOSENESS   X OF PARTS.						OF	· · · · · · · · · · · · · · · · · · ·			_
SHOCK  ACCELAERATION OF 490 m/s², 11 ms DUARATION, SINE HALF-WAVE, 3 CYCLES IN 3 BOTH AXISES; 12 NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  ENVIRONMENTAL CHARACTERISTICS  RAPID CHANGE OF TEMPERATURE -55 → 5 TO 35 −85 → 5 TO 35 °C TIMPERATURE -55 → 5 TO 35 −85 → 5 TO 35 °C TIMPERATURE -55 → 5 TO 35 −85 → 5 TO 15 min UNDER 5 CYCLES.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h. (1) CONTACT RESISTANCE: 30 m/2 MAX. (2) INSULATION RESISTANCE: 30 m/2 MAX. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h. (1) CONTACT RESISTANCE: 30 m/2 MAX. (2) INSULATION RESISTANCE: 500 M/2 MIN. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  PARTS.  RESISTANCE TO 1) FLOW SOLDERING NOS: 15 MAX. (2) INSULATION RESISTANCE: 500 M/2 MIN. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  SOLDERING HEAT (2) SOLDERING IGNOS: 15 MAX. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  SOLDERING HEAT (2) SOLDERING IGNOS: 15 MAX. (3) NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TEMMINALS.  SOLDER SHALL COVER A MINIMUM OF 215 ± 5 °C FOR INSERTION DURATION, 3 SECONDS.  SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED. (3) MAX. (3) MAX. (4) MAX. (4) MAX. (4) MAX. (5) MAX. (5) MAX. (5) MAX. (6) MAX. (6) MAX. (7) MAX. (8) MAX. (9) MA	VIBRATION		The state of the s			② NO	② NO DAMAGE, CRACK OR LOOSENESS			-
ENVIRONMENTAL CHARACTERISTICS  RAPID CHANGE OF TEMPERATURE 55→ 5 TO 35→85→ 5 TO 35 °C  TIME 30→ 5 TO 15 →30→ 5 TO 15 min UNDER 5 CYCLES.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h. (2) INSULATION RESISTANCE: 500MΩ MIN. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h. (1) CONTACT RESISTANCE: 500MΩ MIN. (2) INSULATION RESISTANCE: 500MΩ MIN. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  PARTS.  RESISTANCE TO (1) FLOW SOLDERING SOLDERING SOLDERING SOLDERING HEAT (STEADY STATE)  EXPOSED AT 50 TO 95 %, 96 h. (1) CONTACT RESISTANCE: 500MΩ MIN. (2) INSULATION RESISTANCE: 500MΩ MIN. (3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.  RESISTANCE TO (1) FLOW SOLDERING NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE XX TERMINALS.  250 ± 5 °C MAX. FOR 10 SECONDS. EXCESSIVE LOOSENESS OF THE XX TERMINALS.  250 ± 10 °C, FOR 3 SECONDS.  SOLDERABILITY SOLDER TEMPERATURE, SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED. X  REMARKS  NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT.  NOTE2:NO CONDENSING.  NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION.  COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION.  COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE AND CHECKED HIX. UMEHARA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DRAWN ST. SATO 11. 10. 3 DRAWN ST. SATO 11.	SHOCK		ACCELAERATION OF 490 m/s <sup>2</sup> , 11 ms DUARATION,							
RAPID CHANGE OF TEMPERATURE -55→ 5 TO 35→85→ 5 TO 35 °C TIME 30→ 5 TO 15 →30→ 5 TO 15 min UNDER 5 CYCLES.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  (STEADY ST			SINE HALF-WAVE, 3 CYCLES IN 3 BOTH AXISES;			② NO	© 110 B) WW 101, 010 1011 O11 1000 111200			-
TIME 30→ 5 TO 15 →30→ 5 TO 15 min QUIDER 5 CYCLES.  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  CITING SOLDERING SOME MIN. (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  CITING SOLDERING SOME MIN. (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  CITING SOLDERING SOME MIN. (SOURCE RESISTANCE: 500MΩ MIN. (SOME										
DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  DAMP HEAT (STEADY STATE)  EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.  (STEADY STATE)  DAMP HEAT (STEADY MIN. X  X  DESIGNED  DATE  DA			TIME 30→ 5 TO 15 →30→ 5 TO 15 min			2 INS 3 NO	<ul> <li>② INSULATION RESISTANCE: 500MΩ MIN.</li> <li>③ NO DAMAGE, CRACK OR LOOSENESS</li> </ul>			_
RESISTANCE TO SOLDERING HEAT  1) FLOW SOLDERING SOLDERING HEAT  250±5°CMAX, FOR 10 SECONDS. 250±6°CMAX, FOR 10 SECONDS. 2) SOLDERING IRONS: 290±10°C, FOR 3 SECONDS. SOLDERABILITY  SOLDERED AT SOLDER TEMPERATURE, 215±5°C FOR INSERTION DURATION, 3 SECONDS.  REMARKS NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:NO CONDENSING. NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION.  COUNT  DESCRIPTION OF REVISIONS  DESIGNED  CHECKED  APPROVED  K1, AKIYAMA  11, 03  CHECKED  HK. UMEHARA  11, 03  DRAWN  ST. SAT0  11, 03  DRAWN  ST. SAT0  11, 03  DRAWN  ST. SAT0  SPECIFICATION SHEET  PART NO.  DF13-3P-1, 25DS (77)			EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			① coi	① CONTACT RESISTANCE: 30mΩ MAX.			
RESISTANCE TO SOLDERING 1) FLOW SOLDERING 250±5°CMAX. FOR 10 SECONDS. 250±5°CMAX. FOR 10 SECONDS. 250±5°CMAX. FOR 10 SECONDS. 290±10°C. FOR 3 SECONDS SOLDERABILITY SOLDERED AT SOLDER TEMPERATURE, 215±5°C FOR INSERTION DURATION, 3 SECONDS. SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED. X REMARKS NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:NO CONDENSING. NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DAT CHECKED HK. UMEHARA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DRAWN ST. SATO 11. 03 D	(STEADY STATE)					③ NO	③ NO DAMAGE, CRACK OR LOOSENESS			-
2) SOLDERING IRONS: :290±10°C, FOR 3 SECONDS  SOLDERABILITY  SOLDERED AT SOLDER TEMPERATURE, 215±5°C FOR INSERTION DURATION, 3 SECONDS.  REMARKS NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:NO CONDENSING. NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION.  COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DAT  Unless otherwise specifid , refer to JIS C 5402.  APPROVED KI. AKIYAMA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DRAWN ST. SATO 11. 03 DRAWN ST.			· ·			NO DE				
SOLDERABILITY  SOLDERED AT SOLDER TEMPERATURE, 215±5°C FOR INSERTION DURATION, 3 SECONDS.  REMARKS  NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT.  NOTE2:NO CONDENSING.  NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS  BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND  HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION.  COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DAT  CHECKED HK. UMEHARA 11. 03  DESIGNED TS. KUMAZAWA 11. 03  DRAWN ST. SATO 11. 03  Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-081816-02  SPECIFICATION SHEET PART NO. DF13-3P-1. 25DS (77)	OULDERING MEAT		2) SOLDERING IRONS:			1				-
REMARKS NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:NO CONDENSING. NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION.  COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DAT  Unless otherwise specifid , refer to JIS C 5402.  APPROVED KI. AKIYAMA 11. 03 CHECKED HK. UMEHARA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DRAWN ST. SATO 11. 03	21		SOLDER	215±5°C						-
NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:NO CONDENSING. NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD AFTER PCBBOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERM STORAGE DURING TRANSPORTATION.  COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DAT  Unless otherwise specifid, refer to JIS C 5402.  APPROVED KI. AKIYAMA 11. 03 CHECKED HK. UMEHARA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DRAWN ST. SATO 11. 03 DRAW	REMARKS		FOR INS	ERTION DURATION, 3 SECONDS.	•					
Unless otherwise specifid , refer to JIS C 5402.  APPROVED KI. AKIYAMA 11. 03 CHECKED HK. UMEHARA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DRAWN ST. SATO 11. 03 Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-081816-02  RSPECIFICATION SHEET PART NO. DF13-3P-1. 25DS (77)	NOTE 1:INC NOTE2:NO ( NOTE3:APP BEF( HUM	CONDENSING LY TO THE CO ORE PCB ON MIDITY RANGE	ONDITION BOARD AI IS APPLII	OF LONG TERM STORAGE FOR FTER PCBBOARD , OPERATING T ED FOR INTERM STORAGE DURI	EMPER	RATURE A NSPORT	ND			
Unless otherwise specifid , refer to JIS C 5402.  APPROVED KI. AK I YAMA 11. 03 CHECKED HK. UMEHARA 11. 03 DESIGNED TS. KUMAZAWA 11. 03 DRAWN ST. SATO 11. 03 Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-081816-02  SPECIFICATION SHEET PART NO. DF13-3P-1. 25DS (77)		IT DE	ESCRIPTION	ON OF REVISIONS	DES	IGNED		CHECKED	DA	ATE
CHECKED		nerwise spe	cifid . re	fer to JIS C 5402.			APPROVE	O KI. AKIYAMA	11 (	)3, 25
Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-081816-02  SPECIFICATION SHEET PART NO. DF13-3P-1. 25DS (77)			, · <del>·</del>							
Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-081816-02  SPECIFICATION SHEET PART NO. DF13-3P-1. 25DS (77)							DESIGNED	TS. KUMAZAWA	11.0	3. 25
SPECIFICATION SHEET PART NO. DF13-3P-1. 25DS (77)							DRAWN	ST. SATO	11.0	3. 25
NO STEEL STREET	Note QT:Q	ualification Tes	t AT:Ass	urance Test X:Applicable Test	[	DRAWING NO.		ELC4-081816-02		
	HRS	SF	PECIFI	CATION SHEET	PAF	RT NO.	DF13-3P-1. 25DS (77)		)	
FORM HD0011-2-1			OSE EI	LECTRIC CO., LTD.	COE	DE NO.	CL536		Δ	1/1